

The Effect of Trim and Form Process on the Plated Leads of IC Packages

by

Muhammad Saifuldin Bin Bakri

Dissertation submitted in partial fulfillment of
the requirements for the
Bachelor of Engineering (Hons)
(Mechanical Engineering)

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Universiti Teknologi PETRONAS
Bandar Seri Iskandar
31750 Tronoh
Perak Darul Ridzuan

CERTIFICATION OF APPROVAL

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Approved by,

(Dr. Azmi bin Abdul Wahab)

UNIVERSITI TEKNOLOGI PETRONAS

TRONOH, PERAK

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CERTIFICATION OF ORIGINALITY

This is to certify that I am responsible for the work submitted in this project, that the original work is my own except as specified in the references and acknowledgements, and that the original work contained herein have not been undertaken or done by unspecified sources or persons.

MUHAMMAD SAIFULDIN BIN BAKRI